

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D $T_A = +25^\circ\text{C}$
60V	3.0Ω @ $V_{GS} = 10\text{V}$	400mA
	4.0Ω @ $V_{GS} = 5\text{V}$	330mA

Features and Benefits

- N-Channel MOSFET
- Low On-Resistance
- Low Gate-Threshold Voltage
- Low-Input Capacitance
- Fast Switching Speed
- Small-Surface Mount Package
- **ESD Protected Gate, 1.2kV HBM**
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

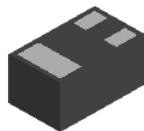
- DC-DC Converters
- Power Management Functions
- Battery Operated Systems and Solid-State Relays
Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.

Mechanical Data

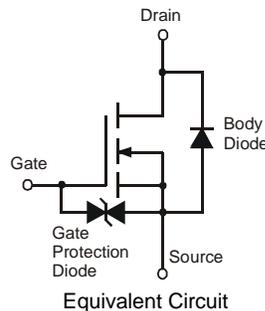
- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 **(e4)**
- Weight: 0.001 grams (Approximate)



X1-DFN1006-3



Bottom View



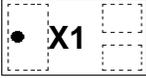
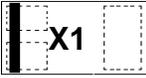
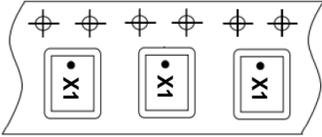
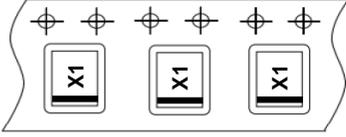
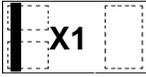
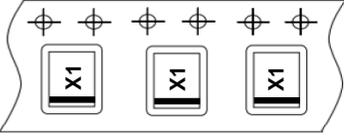
Top View
Pin Configuration

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN65D8LFB-7	X1-DFN1006-3	3,000/Tape & Reel
DMN65D8LFB-7B	X1-DFN1006-3	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information

<p>DMN65D8LFB-7</p>	<div style="display: flex; justify-content: space-around; align-items: flex-start;"> <div style="text-align: center;">  <p>Top View Dot Denotes Drain Side</p> </div> <div style="text-align: center;"> <p>From date code 1527 (YYWW), this changes to:</p>  <p>Top View Bar Denotes Gate and Source Side</p> </div> </div> <div style="display: flex; justify-content: space-around; margin-top: 20px;">   </div>
<p>DMN65D8LFB-7B</p>	<div style="text-align: center; margin-bottom: 20px;">  <p>Top View Bar Denotes Gate and Source Side</p> </div> <div style="display: flex; justify-content: space-between; align-items: center;">  <div style="text-align: right;"> <p>X1 = Part Marking Code</p> </div> </div>

Maximum Ratings

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			V_{GSS}	± 20	V
Continuous Drain Current (Note 4) $V_{GS} = 10V$	Steady State	$T_A = +25^\circ C$	I_D	260	mA
		$T_A = +70^\circ C$		210	
Continuous Drain Current (Note 5) $V_{GS} = 10V$	Steady State	$T_A = +25^\circ C$	I_D	400	mA
		$T_A = +70^\circ C$		310	

Thermal Characteristics

Characteristic	Symbol	Value	Units
Power Dissipation, @ $T_A = +25^\circ C$ (Note 4)	P_D	430	mW
Thermal Resistance, Junction to Ambient @ $T_A = +25^\circ C$ (Note 4)	$R_{\theta JA}$	290	$^\circ C/W$
Power Dissipation, @ $T_A = +25^\circ C$ (Note 5)	P_D	840	mW
Thermal Resistance, Junction to Ambient @ $T_A = +25^\circ C$ (Note 5)	$R_{\theta JSA}$	147	$^\circ C/W$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$

Electrical Characteristics (@ $T_A = +25^\circ C$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	60	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current $T_J = +25^\circ C$	I_{DSS}	-	-	0.1	μA	$V_{DS} = 60V, V_{GS} = 0V$
Gate-Body Leakage	I_{GSS}	-	-	± 10	μA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(th)}$	1.2	-	2.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Static Drain-Source On-Resistance	$R_{DS(on)}$	-	-	3.0	Ω	$V_{GS} = 10V, I_D = 0.115A$ $V_{GS} = 5V, I_D = 0.1115A$
				4.0		
Forward Transfer Admittance	$ Y_{fs} $	80	320	-	mS	$V_{DS} = 10V, I_D = 0.115A$
Diode Forward Voltage	V_{SD}	-	0.7	1.2	V	$V_{GS} = 0V, I_S = 0.115A$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C_{iss}	-	25	-	pF	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$
Output Capacitance	C_{oss}	-	4.7	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	2.5	-	pF	
Turn-On Delay Time	$t_{D(on)}$	-	3.27	-	ns	$V_{DD} = 30V, V_{GEN} = 10V,$ $R_{GEN} = 25\Omega, I_D = 0.115A$
Turn-On Rise Time	t_r	-	3.15	-	ns	
Turn-Off Delay Time	$t_{D(off)}$	-	12.025	-	ns	
Turn-Off Fall Time	t_f	-	6.29	-	ns	

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout, single-sided.
 - Device mounted on 2" x 2" FR-4 PCB with high coverage 2oz. Copper, single-sided.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

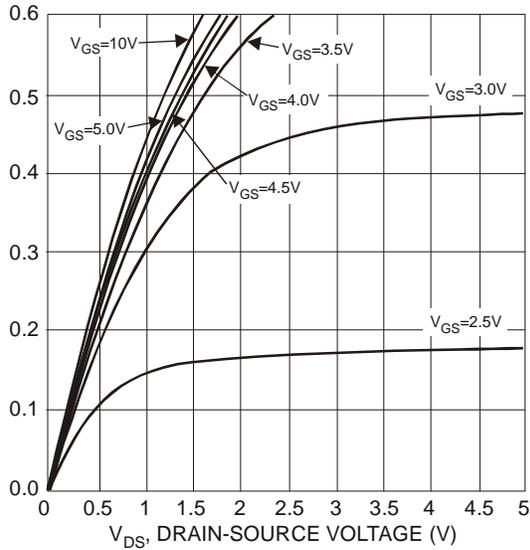


Fig. 1 Typical Output Characteristics

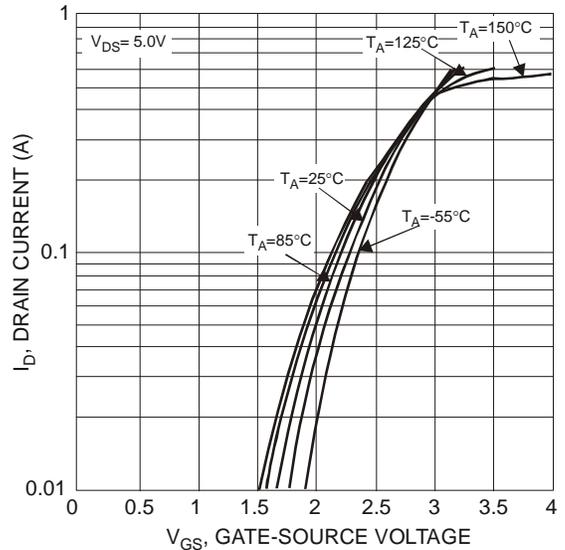


Fig. 2 Typical Transfer Characteristics

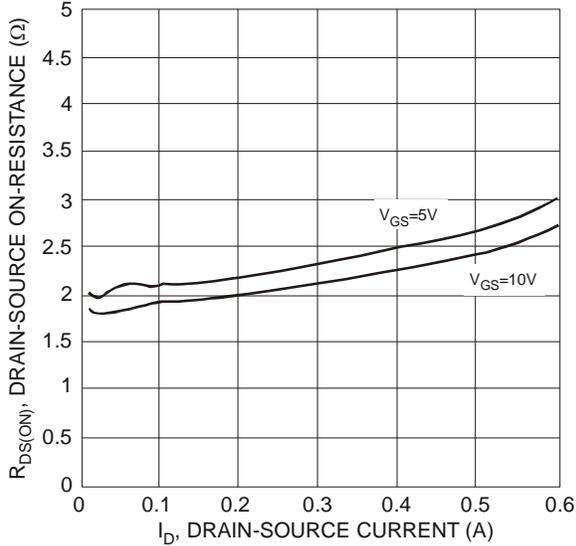


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Charge

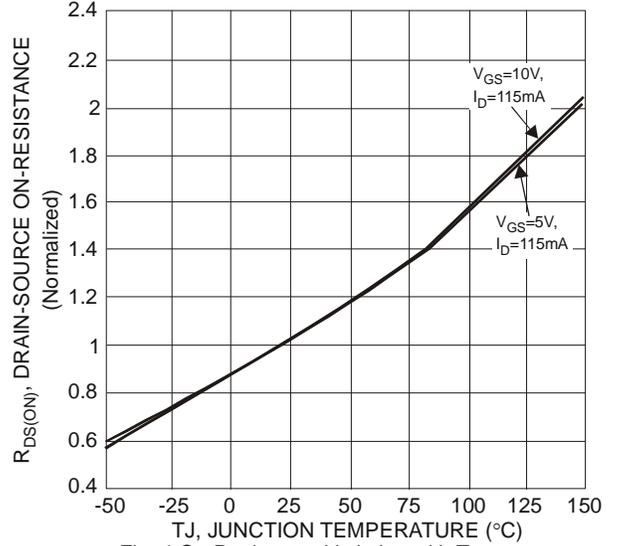


Fig. 4 On-Resistance Variation with Temperature

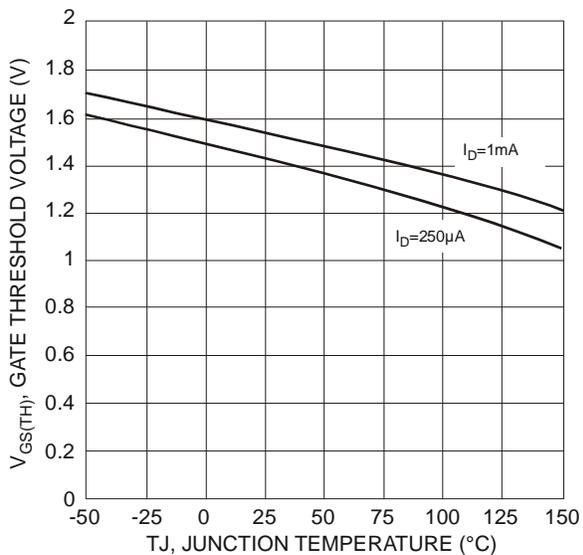


Fig. 5 Gate Threshold Variation vs. Ambient Temperature

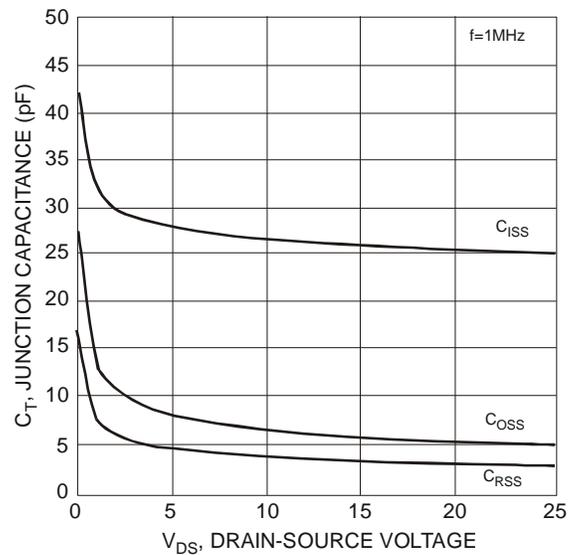


Fig. 6 Typical Junction Capacitance

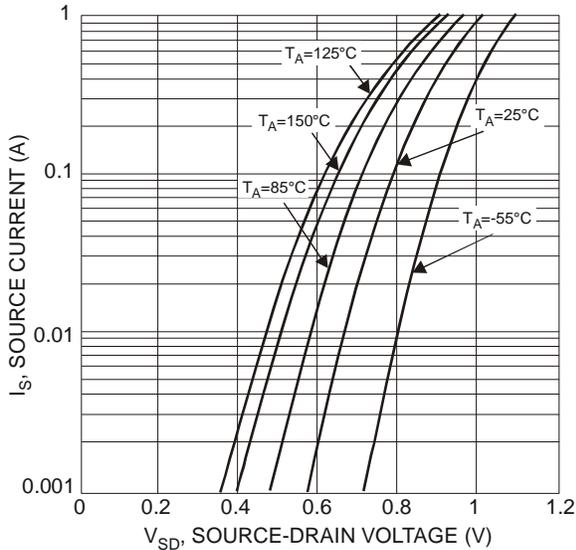
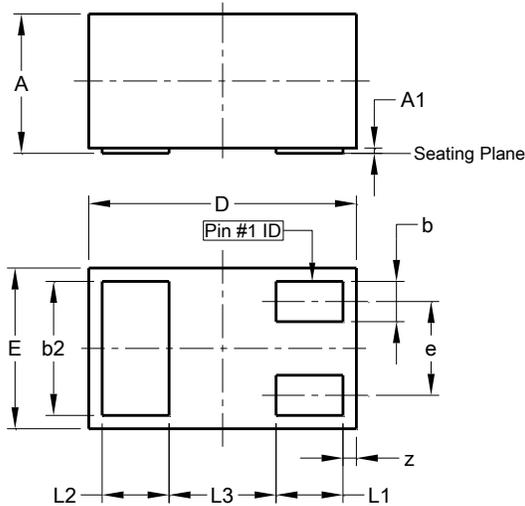


Fig. 7 Diode Forward Voltage vs. Current

Package Outline Dimensions

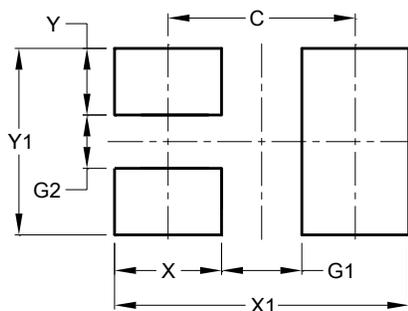
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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